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(71) Applicant (for all designated States except US): **NIPSEA TECHNOLOGIES PTE LTD** [SG/SG]; 16 Joo Koon Crescent, Singapore 629018 (SG).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **WANG, Shaofeng** [SG/SG]; Blk 21, #03-04 Rosewood Drive, Singapore 737917 (SG). **SEOW, Swee How** [MY/SG]; Blk 560, #05-76 Choa Chu Kang North 6, Singapore 680560 (SG). **DOU, Zeling** [SG/SG]; Blk 512, #07-253 Choa Chu Kang St 51, Singapore 680512 (SG). **CHOATE, Thomas, F.** [US/US]; c/o Nanovere Technologies, 4724 Caroga Drive, Pinkney, MI 48114 (US). **YE, Xiaoqun** [CN/SG]; Blk 28B, #34-41 Dover Crescent, Singapore 132028 (SG).

(74) Agent: **ELLA CHEONG SPRUSON & FERGUSON (SINGAPORE) PTE LTD**; Robinson Road Post Office, P.O. Box 1531, Singapore 903031 (SG).

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(54) Title: A HIGH SOLIDS CONTENT DENDRIMER POLYMER COMPOSITION.

(57) Abstract: The present invention relates to a polymer composition comprising: (i) one or more dendritic polymers; and (ii) a reactive diluent that is capable of being chemically coupled to the functional groups of the dendritic polymers, wherein when the dendritic polymer is coupled to the reactive diluent in the presence of a cross-linker, a polymerized solid is formed at high concentrations in a liquid medium. The present invention further relates to methods of preparing the polymer composition and its use in forming coatings.

